PCN Number:		20230329000.1				PC N I	Date:	March 30, 2023	
Title:		d compound for Select package Device							
				Dept:	Quality Services				
Proposed 1 <sup>st</sup> Ship Date:		June 30, 2023		•	Sample request accepted until:		iests	Apr 30, 2023	
*Sample	requests received	after (Apr 30, 2	2023) wi	II not be su	•				
Change									
	sembly Site		_	esign		ᆜᆜ		Bump Site	
	☐ Assembly Process ☐ Assembly Materials		Data Shee					Wafer Bump Material Wafer Bump Process	
	chanical Specificat	ion	Part number  Test Site		riange	Wafer Fab Site			
	☐ Packing/Shipping/Labe							Wafer Fab Materials	
					□ Waf		Wafer F	afer Fab Process	
			PCN	<b>Details</b>					
Descrip	tion of Change:								
Texas Instruments is pleased to announce the qualification of new mold compound for the device listed in "Product affected" section below. Device will remain in current assembly facility and piece part changes as follows:									
	Material	Current			Proposed				
M	1old compound	10131	101319573			101385017			
Reason	for Change:								
	ty of supply.								
	ated impact on Fit	Form Funct	ion Ou	ality or Rel	lia hility	(nosit	tive / neg	ative):	
None.	red impact on the	, rom, runce	ion, Qui	ancy or ite	ila Dilicy	(posit	ive / neg	utive).	
Impact	on Environmenta	l Ratings							
Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.									
	RoHS	REA	СН	Gre	en Stati	us	IEC	62474	
$\boxtimes$	No Change	⊠ No Chan	ge	⊠ No (	Change		⊠ No Ch	nange	
Anticipa	ated impact on Ma	terial Declara	ation						
	s to product iden			m this PC	N:				
None.									
Product	Affected:								
ADC07E	01520CIYB/NOPB	ADC08500CIYB/	/NOPB	ADC08D15	00CIYB/N	ОРВ	ADC08	D500CIYB/S70029	<del>)</del> 52
ADC081	.000CIYB/NOPB	ADC08B3000CI	YB/NOPB	ADC08D15	20CIYB/N	ОРВ	ADC08	D502CIYB/NOPB	
ADC081	500CIYB/NOPB	ADC08D1000CI	YB/NOPB	ADC08D15	20CIYB/S	70023	96 LM978	35CIYB/NOPB	
ADC083	000CIYB/NOPB	ADC08D1010DI	YB/NOPB	ADC08D50	OCIYB/NC	PB			
ADC083	000CIYB/S7002214	ADC08D1020CI	YB/NOPB	ADC08D50	0CIYB/S7	00255	4		

## **Qualification Report**

Approve Date 07-Feb-2023

## **Qualification Results**

## Data Displayed as: Number of lots / Total sample size / Total failed

Туре	#	Test Name	Condition	Duration	Qual Device: <u>ADC081000CIYB/NOPB</u>
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	3/231/0
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	3/231/0
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	3/231/0
SD	С3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes); PB- Free Solder;	-	3/66/0
FTY	E6	Final Test Yield	•	-	3/3/0

QBS: Qual By Similarity

Qual Device A DC081000CIYB/NOPB is qualified at MSL3 260C

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status: Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail				
WW PCN Team	PCN ww admin team@list.ti.com				

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